



Material Content Data Sheet



Sales Product Name		BTS5210G		Issued		29. August 2013		
MA#		MA000990170						
Package		PG-DSO-14-37		Weight*		144.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.505	2.43	2.43	24269	24269
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		104	
	non noble metal	zinc	7440-66-6	0.060	0.04		418	
	non noble metal	iron	7439-89-6	1.207	0.84		8358	
wire	non noble metal	copper	7440-50-8	49.007	33.94	34.83	339366	348246
	noble metal	gold	7440-57-5	1.687	1.17	1.17	11679	11679
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1186
plastics	plastics	epoxy resin	-	7.880	5.46		54568	
	inorganic material	silicondioxide	60676-86-0	77.601	53.73	59.31	537378	593132
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8491	8491
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7131	7131
glue	plastics	epoxy resin	-	0.178	0.12		1234	
	noble metal	silver	7440-22-4	0.840	0.58	0.70	5818	7052
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com